# PRODUCT/PROCESS CHANGE NOTICE (PCN)

<table>
<thead>
<tr>
<th>PCN #:</th>
<th>L0307-02</th>
<th>DATE:</th>
<th>8/1/03</th>
</tr>
</thead>
<tbody>
<tr>
<td>Product Affected:</td>
<td>IDT74FCT3244, IDT74FCT3245, IDT74FCT244T, IDT74FCT245T</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Date Effective:** October 31, 2003

**Contact:** Bimla Paul

**Title:** Quality Assurance Manager

**Phone #:** (408)-654-6419

**Fax #:** (408)-492-8362

**E-mail:** bimla.paul@idt.com

**Description and Purpose of Change:**
- **Die Technology**: Device stepping (revision) change from "PB" to "Z" on selected Logic products.
- **Wafer Fabrication Process**: There is no change in die technology.
- **Assembly Process**: 
- **Equipment**: 
- **Material**: Please see attachment for the affected part numbers and qual data.
- **Testing**: 
- **Manufacturing Site**: 
- **Data Sheet**: 
- **Other**: 

**Reliability/Qualification Summary:**
Please see attachment for qualification data.

**Customer Acknowledgment of Receipt:**
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

**Customer:** ____________________________

**Name/Date:** ____________________________

**E-Mail Address:** ____________________________

**Title:** ____________________________

**Phone# /Fax#:** ____________________________

**Customer Comments:** ____________________________

**IDT Acknowledgment of Receipt:**

RECD. BY: ____________________________

DATE: ____________________________

IDT FRA-1509-01 REV. 00 09/18/01 Page 1 of 1 Refer To QCA-1795
PRODUCT/PROCESS CHANGE NOTICE (PCN)
ATTACHMENT - PCN #: L0307-02

PCN Type: Die Revision Change

Data Sheet Change: None

Detail of Change: Device stepping (revision) change from "PB" to "Z" on selected Logic products. There is no change in die technology or fab location.

The following devices are affected by this change. All packages and speed grades are affected.

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Old Stepping</th>
<th>New Stepping</th>
</tr>
</thead>
<tbody>
<tr>
<td>IDT74FCT3244</td>
<td>PB</td>
<td>Z</td>
</tr>
<tr>
<td>IDT74FCT3245</td>
<td>PB</td>
<td>Z</td>
</tr>
<tr>
<td>IDT74FCT244T</td>
<td>PB</td>
<td>Z</td>
</tr>
<tr>
<td>IDT74FCT245T</td>
<td>PB</td>
<td>Z</td>
</tr>
</tbody>
</table>

Conversion Schedule:

Die Revision  Sample Availability:  Production Shipment:
Z Stepping    August 15, 2003    October 31, 2003
Qualification Plans: Following reliability tests were performed on the process family. The qualification results are as follow:

<table>
<thead>
<tr>
<th>Test Description</th>
<th>Test Method</th>
<th>Required Sample/ # Fails</th>
<th>Process Family Data</th>
<th>Z Stepping Data</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating Life Test: Dynamic</td>
<td>Mil-Std 883 Method 1005</td>
<td>116/0</td>
<td>116/0</td>
<td>ECD Sept 15, 03</td>
</tr>
<tr>
<td>1000 hrs @ 125°C or equivalent</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Bake &amp; Ball Shear</td>
<td>EIA/JESD 22 B116</td>
<td>5/0</td>
<td>5/0</td>
<td></td>
</tr>
<tr>
<td>Temp Cycle -65°C to +150°C, 500 Cyc</td>
<td>JESD 22 A104</td>
<td>45/0</td>
<td>45/0</td>
<td></td>
</tr>
<tr>
<td>ESD Human Body Model</td>
<td>Mil-Std 883 Method 3015</td>
<td>3/0</td>
<td>3000V</td>
<td>ECD Sept 15, 03</td>
</tr>
<tr>
<td>ESD Charged Device Model</td>
<td>JEDEC 22-101</td>
<td>3/0</td>
<td>1000V</td>
<td>ECD Sept 15, 03</td>
</tr>
<tr>
<td>Latch up: (Tested to 1.5X Vcc)</td>
<td>EIA/JESD STD-78</td>
<td>10/0</td>
<td>10/0</td>
<td>ECD Sept 15, 03</td>
</tr>
</tbody>
</table>

ECD = Estimated Completion Date

Characterization Data:
Characterization data is available upon request.